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(30) Priority:	(71) Applicant: <b>SUMITOMO METAL M LTD</b>
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**(54) FORMATION OF PARTIAL CONDUCTIVE FILM**

(57) Abstract:

**PURPOSE:** To form a conductive film which can be bonded at the tip of a lead by pressurizing and heating a polymer film with a conductive resin composition to a lead frame, exfoliating the film, retaining the composition, and thermally curing the composition.

**CONSTITUTION:** A polymer film coated with conductive resin composition A in a large area including an island on the tip of an inner lead is so adhered on one main face of a lead frame as to bring into contact with the composition A in coincidence in area. The area part is pressurized and/or heated from the side of the film thereby to bring the composition A in close contact with the area part. The film is exfoliated, the composition A remains on the tip of the inner lead and the island, and

- thermally cured. Thus, a conductive film which can be wire bonded is formed on the end of the inner lead.

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